

SLOVENSKI STANDARD

SIST EN 60191-6-13:2017

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Nadomešča:

SIST EN 60191-6-13:2008

**Standardizacija mehanskih lastnosti polprevodniških elementov - 6-13. del:
Smernica za načrtovanje zgoraj odprtih podstavkov za fini raster mreže krogličnih
priključkov in fini raster mreže priključkov v ravnini (FBGA/FLGA) (IEC 60191-6-
13:2016)**

Mechanical standardization of semiconductor devices - Part 6-13: Design guideline of
open-top type sockets for Fine-pitch Ball Grid Array and Fine-pitch Land Grid Array
(FBGA/FLGA) (IEC 60191-6-13:2016)

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Mechanische Normung von Halbleiterbauelementen - Teil 6-13: Konstruktionsleitfaden für
Open-top-Fassungen für Feinraster-Ball-Grid-Array und Feinraster-Land-Grid-Array
(FBGA/FLGA) (IEC 60191-6-13:2016)

Normalisation mécanique des dispositifs à semiconducteurs - Partie 6-13: Guide de
conception pour les supports sans couvercle pour les boîtiers matriciels à billes et à pas
fins et les boîtiers matriciels à zone de contact plate et à pas fins (FBGA/FLGA) (IEC
60191-6-13:2016)

Ta slovenski standard je istoveten z: EN 60191-6-13:2016

ICS:

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
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en

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 60191-6-13

November 2016

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Supersedes EN 60191-6-13:2007

English Version

**Mechanical standardization of semiconductor devices -
Part 6-13: Design guideline of open-top-type sockets for Fine-
pitch Ball Grid Array (FBGA) and Fine-pitch Land Grid Array
(FLGA)
(IEC 60191-6-13:2016)**

Normalisation mécanique des dispositifs à semiconducteurs
- Partie 6-13: Guide de conception pour les supports sans
couvercle pour les boîtiers matriciels à billes et à pas fins
(FBGA) et les boîtiers matriciels à zone de contact plate et
à pas fins (FLGA)
(IEC 60191-6-13:2016)

Mechanische Normung von Halbleiterbauelementen -
Teil 6-13: Konstruktionsleitfaden für Open-top-Fassungen
für Feinraster-Ball-Grid-Array und Feinraster-Land-Grid-
Array (FBGA/FLGA)
(IEC 60191-6-13:2016)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

EN 60191-6-13:2016**European foreword**

The text of document 47D/878/FDIS, future edition 2 of IEC 60191-6-13, prepared by SC 47D "Semiconductor devices packaging" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60191-6-13:2016.

The following dates are fixed:

- latest date by which the document has to be (dop) 2017-08-01
implemented at national level by
publication of an identical national
standard or by endorsement
- latest date by which the national (dow) 2019-11-01
standards conflicting with the
document have to be withdrawn

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191-2	-	Mechanical standardization of semiconductor devices - Part 2: Dimensions	-	-
IEC 60191-6	-	Mechanical standardization of semiconductor devices - Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages	EN 60191-6	-

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Edition 2.0 2016-09

INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Mechanical standardization of semiconductor devices –
Part 6-13: Design guideline of open-top-type sockets for Fine-pitch Ball Grid
Array (FBGA) and Fine-pitch Land Grid Array (FLGA)**

**Normalisation mécanique des dispositifs à semiconducteurs –
Partie 6-13: Guide de conception pour les supports sans couvercle pour les
boîtiers matriciels à billes et à pas fins (FBGA) et les boîtiers matriciels à zone
de contact plate et à pas fins (FLGA)**

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CONTENTS

FOREWORD.....	3
INTRODUCTION.....	5
1 Scope.....	6
2 Normative references.....	6
3 Terms and definitions	6
4 Socket code	6
4.1 Construction of socket code	6
4.2 Symbols.....	7
4.2.1 Semiconductor sockets symbol.....	7
4.2.2 Socket type symbol.....	7
4.2.3 Socket nominal dimension symbol	7
4.2.4 Number of terminal arrays	7
4.2.5 Terminal pitch	7
5 Terminal number	7
6 Socket nominal dimension	8
7 Socket length and width.....	8
8 Reference symbols and schematics.....	8
8.1 Outline drawings	8
8.2 Reference symbols and schematics of recommended socket mounting pattern on printed circuit board	11
8.3 Overall dimensions.....	12
8.4 Recommended dimensions of socket mounting pattern on printed circuit board	17
9 Individual outline drawing standard registration	18
Figure 1 – Outline drawings of the socket.....	9
Figure 2 – Outline drawings for the definition of terminal diameter	10
Figure 3 – Applicable package outline	10
Figure 4 – Socket mounting pattern.....	11
Table 1 – Overview for the different socket groups	8
Table 2 – Overall dimensions (1 of 2)	12
Table 3 – Socket dimensions for Group 1, 2 and 3 (square socket) (1 of 2)	14
Table 4 – Socket dimension for Group 4 (square or rectangular socket)	16
Table 5 – Socket mounting dimensions.....	17
Table 6 – Registration table	18

INTERNATIONAL ELECTROTECHNICAL COMMISSION

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

**Part 6-13: Design guideline of open-top-type sockets for
Fine-pitch Ball Grid Array (FBGA) and Fine-pitch Land Grid Array (FLGA)**

FOREWORD

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International Standard IEC 60191-6-13 has been prepared by subcommittee 47D: Semiconductor devices packaging, of IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2007. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) BGA package nominal length and width have been newly expanded to 43 mm and 43 mm, respectively. Accordingly, six socket sizes have been added to the socket group numbers 1, 2 and 3, and twenty-two socket sizes have been added to the socket group number 4.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/878/FDIS	47D/885/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all the parts in the IEC 60191 series, under the general title *Mechanical standardization of semiconductor devices*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTRODUCTION

This part of IEC 60191 aims to standardize the outer dimensions of the sockets for FBGA and FLGA, where leading-edge developments are aggressively innovated, to establish their compatibility with the needs of the surface-mount industry that is globally expanding due to enhanced functions and performances of electrical devices.

For defining each dimension, the target was to indicate the standard design value which has the concept of the design centre as much as possible, aiming to enhance the function as a standardization index.

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